

### REMARKS

Upon entry of the amendments, only Claim 24 will be pending. Applicants seek to amend Claim 24 to correct an error that went undetected until now -- each lead is connected to a bond pad and extends over the surface of the chip, not over the bond pads. None of the embodiments shown in the drawings include leads extending over the bond pads. Applicants also seek to amend Claim 24 to make it clear that the insulating material and encapsulating material are discrete elements to avoid any suggestion that the encapsulating material in Ichiyama might somehow be deemed to satisfy both claim elements.

Ichiyama does not teach the combination of three "conductive paths" in the structural configuration recited in Claim 24, without regard to whether or not the third path is a solder ball or some other conductor. The Examiner's remarks to date do not address all of the limitations of Claim 24 and, therefore, there has been no specific showing that the combination of Ichiyama and Ehata support the Section 103 rejection of Claim 24.

Applicants believe the case is in condition for allowance. The foregoing is believed to be a complete response to the outstanding office action.

Respectfully submitted,



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